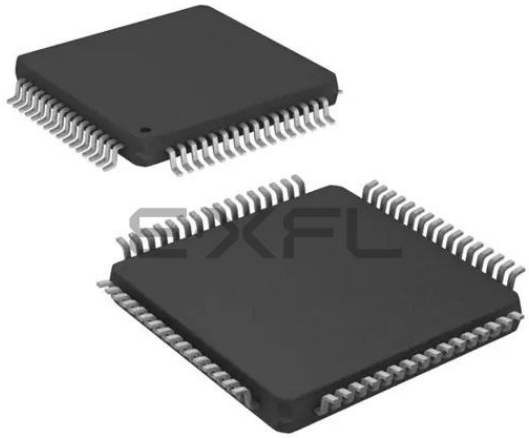

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	53
Program Memory Size	48KB (24K x 16)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	3.8K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf6525-i-pt

TABLE 1-2: PIC18F6525/6621/8525/8621 PINOUT I/O DESCRIPTIONS

Pin Name	Pin Number		Pin Type	Buffer Type	Description
	PIC18F6X2X	PIC18F8X2X			
$\overline{MCLR}$/VPP/RG5(9)	7	9			Master Clear (input) or programming voltage (output).
$\overline{MCLR}$			I	ST	Master Clear (Reset) input. This pin is an active-low Reset to the device.
VPP			P	—	Programming voltage input.
RG5			I	ST	Digital input.
OSC1/CLKI	39	49			Oscillator crystal or external clock input.
OSC1			I	CMOS/ST	Oscillator crystal input or external clock source input. ST buffer when configured in RC mode; otherwise CMOS.
CLKI			I	CMOS	External clock source input. Always associated with pin function OSC1 (see OSC1/CLKI, OSC2/CLKO pins).
OSC2/CLKO/RA6	40	50			Oscillator crystal or clock output.
OSC2			O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal oscillator mode.
CLKO			O	—	In RC mode, OSC2 pin outputs CLKO which has 1/4 the frequency of OSC1 and denotes the instruction cycle rate.
RA6			I/O	TTL	General purpose I/O pin.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; OD = Open-Drain (no P diode to VDD)

Note 1: Alternate assignment for ECCP2/P2A in PIC18F8525/8621 devices when CCP2MX (CONFIG3H<0>) is not set (all Program Memory modes except Microcontroller).

2: Default assignment for ECCP2/P2A when CCP2MX is set (all devices).

3: External memory interface functions are only available on PIC18F8525/8621 devices.

4: Default assignment for P1B/P1C/P3B/P3C for PIC18F8525/8621 devices when ECCPMX (CONFIG3H<1>) is set and for all PIC18F6525/6621 devices.

5: Alternate assignment for ECCP2/P2A in PIC18F8525/8621 devices when CCP2MX is not set (Microcontroller mode).

6: PORTH and PORTJ (and their multiplexed functions) are only available on PIC18F8525/8621 devices.

7: Alternate assignment for P1B/P1C/P3B/P3C for PIC18F8525/8621 devices when ECCPMX (CONFIG3H<1>) is not set.

8: AVDD must be connected to a positive supply and AVSS must be connected to a ground reference for proper operation of the part in user or ICSP™ modes. See parameter D001 for details.

9: RG5 is multiplexed with $\overline{MCLR}$ and is only available when the $\overline{MCLR}$ Resets are disabled.

TABLE 1-2: PIC18F6525/6621/8525/8621 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number		Pin Type	Buffer Type	Description
	PIC18F6X2X	PIC18F8X2X			
					PORTJ is a bidirectional I/O port(6).
RJ0/ALE	—	62			
RJ0			I/O	ST	Digital I/O.
ALE			O	TTL	External memory address latch enable.
RJ1/$\overline{OE}$	—	61			
RJ1			I/O	ST	Digital I/O.
$\overline{OE}$			O	TTL	External memory output enable.
RJ2/$\overline{WRL}$	—	60			
RJ2			I/O	ST	Digital I/O.
$\overline{WRL}$			O	TTL	External memory write low control.
RJ3/$\overline{WRH}$	—	59			
RJ3			I/O	ST	Digital I/O.
$\overline{WRH}$			O	TTL	External memory write high control.
RJ4/BA0	—	39			
RJ4			I/O	ST	Digital I/O.
BA0			O	TTL	System bus byte address 0 control.
RJ5/$\overline{CE}$	—	40			
RJ5			I/O	ST	Digital I/O
$\overline{CE}$			O	TTL	External memory access indicator.
RJ6/$\overline{LB}$	—	41			
RJ6			I/O	ST	Digital I/O.
$\overline{LB}$			O	TTL	External memory low byte select.
RJ7/$\overline{UB}$	—	42			
RJ7			I/O	ST	Digital I/O.
$\overline{UB}$			O	TTL	External memory high byte select.
VSS	9, 25, 41, 56	11, 31, 51, 70	P	—	Ground reference for logic and I/O pins.
VDD	10, 26, 38, 57	12, 32, 48, 71	P	—	Positive supply for logic and I/O pins.
AVSS(8)	20	26	P	—	Ground reference for analog modules.
AVDD(8)	19	25	P	—	Positive supply for analog modules.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; OD = Open-Drain (no P diode to VDD)

Note 1: Alternate assignment for ECCP2/P2A in PIC18F8525/8621 devices when CCP2MX (CONFIG3H<0>) is not set (all Program Memory modes except Microcontroller).

2: Default assignment for ECCP2/P2A when CCP2MX is set (all devices).

3: External memory interface functions are only available on PIC18F8525/8621 devices.

4: Default assignment for P1B/P1C/P3B/P3C for PIC18F8525/8621 devices when ECCPMX (CONFIG3H<1>) is set and for all PIC18F6525/6621 devices.

5: Alternate assignment for ECCP2/P2A in PIC18F8525/8621 devices when CCP2MX is not set (Microcontroller mode).

6: PORTH and PORTJ (and their multiplexed functions) are only available on PIC18F8525/8621 devices.

7: Alternate assignment for P1B/P1C/P3B/P3C for PIC18F8525/8621 devices when ECCPMX (CONFIG3H<1>) is not set.

8: AVDD must be connected to a positive supply and AVSS must be connected to a ground reference for proper operation of the part in user or ICSP™ modes. See parameter D001 for details.

9: RG5 is multiplexed with $\overline{MCLR}$ and is only available when the $\overline{MCLR}$ Resets are disabled.

7.0 DATA EEPROM MEMORY

The data EEPROM is readable and writable during normal operation over the entire VDD range. The data memory is not directly mapped in the register file space. Instead, it is indirectly addressed through the Special Function Registers (SFR).

There are five SFRs used to read and write the program and data EEPROM memory. These registers are:

- EECON1
- EECON2
- EEDATA
- EEADRH
- EEADR

The EEPROM data memory allows byte read and write. When interfacing to the data memory block, EEDATA holds the 8-bit data for read/write. EEADR and EEADRH hold the address of the EEPROM location being accessed. These devices have 1024 bytes of data EEPROM with an address range from 00h to 3FFh.

The EEPROM data memory is rated for high erase/write cycles. A byte write automatically erases the location and writes the new data (erase-before-write). The write time is controlled by an on-chip timer. The write time will vary with voltage and temperature, as well as from chip-to-chip. Please refer to parameter D122 (**Section 27.0 "Electrical Characteristics"**) for exact limits.

7.1 EEADR and EEADRH

The address register pair can address up to a maximum of 1024 bytes of data EEPROM. The two Most Significant bits of the address are stored in EEADRH, while the remaining eight Least Significant bits are stored in EEADR. The six Most Significant bits of EEADRH are unused and are read as '0'.

7.2 EECON1 and EECON2 Registers

EECON1 is the control register for EEPROM memory accesses.

EECON2 is not a physical register. Reading EECON2 will read all '0's. The EECON2 register is used exclusively in the EEPROM write sequence.

Control bits RD and WR initiate read and write operations, respectively. These bits cannot be cleared, only set in software. They are cleared in hardware at the completion of the read or write operation. The inability to clear the WR bit in software prevents the accidental or premature termination of a write operation.

Note:	During normal operation, the WRERR bit is read as '1'. This can indicate that a write operation was prematurely terminated by a Reset, or a write operation was attempted improperly.

The WREN bit, when set, will allow a write operation. On power-up, the WREN bit is clear. The WRERR bit is set when a write operation is interrupted by a $\overline{\text{MCLR}}$ Reset or a WDT Time-out Reset during normal operation. In these situations, the user can check the WRERR bit and rewrite the location. It is necessary to reload the data and address registers (EEDATA and EEADR) due to the Reset condition forcing the contents of the registers to zero.

Note:	Interrupt flag bit, EEIF in the PIR2 register, is set when write is complete. It must be cleared in software.

TABLE 10-7: PORTD FUNCTIONS

Name	Bit#	Buffer Type	Function
RD0/AD0(2)/PSP0	bit 0	ST/TTL(1)	Input/output port pin, address/data bus bit 0 or Parallel Slave Port bit 0.
RD1/AD1(2)/PSP1	bit 1	ST/TTL(1)	Input/output port pin, address/data bus bit 1 or Parallel Slave Port bit 1.
RD2/AD2(2)/PSP2	bit 2	ST/TTL(1)	Input/output port pin, address/data bus bit 2 or Parallel Slave Port bit 2.
RD3/AD3(2)/PSP3	bit 3	ST/TTL(1)	Input/output port pin, address/data bus bit 3 or Parallel Slave Port bit 3.
RD4/AD4(2)/PSP4	bit 4	ST/TTL(1)	Input/output port pin, address/data bus bit 4 or Parallel Slave Port bit 4.
RD5/AD5(2)/PSP5	bit 5	ST/TTL(1)	Input/output port pin, address/data bus bit 5 or Parallel Slave Port bit 5.
RD6/AD6(2)/PSP6	bit 6	ST/TTL(1)	Input/output port pin, address/data bus bit 6 or Parallel Slave Port bit 6.
RD7/AD7(2)/PSP7	bit 7	ST/TTL(1)	Input/output port pin, address/data bus bit 7 or Parallel Slave Port bit 7.

Legend: ST = Schmitt Trigger input, TTL = TTL input

Note 1: Input buffers are Schmitt Triggers when in I/O mode and TTL buffers when in System Bus or Parallel Slave Port mode.

2: External memory interface functions are only available on PIC18F8525/8621 devices.

TABLE 10-8: SUMMARY OF REGISTERS ASSOCIATED WITH PORTD

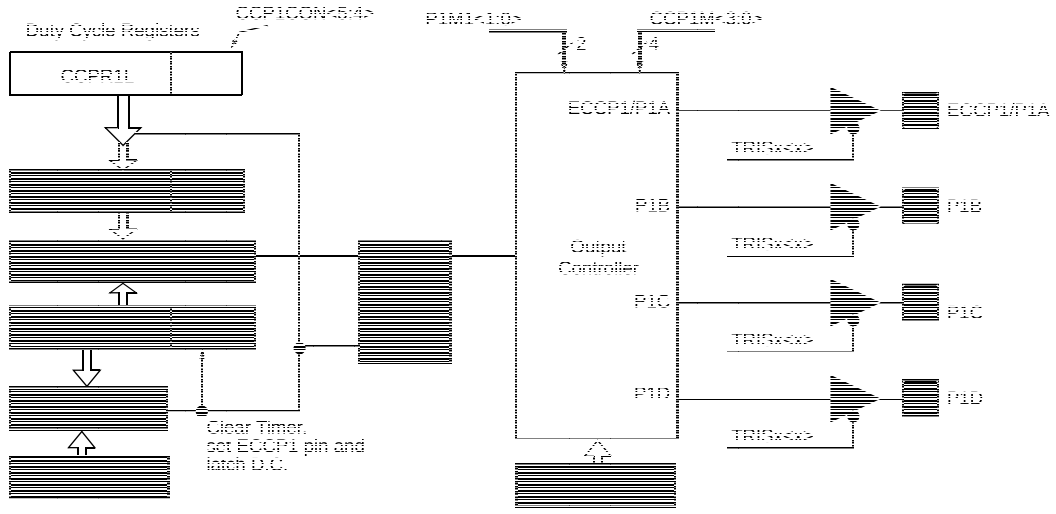
Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
PORTD	RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0	xxxx xxxx	uuuu uuuu
LATD	LATD Data Output Register								xxxx xxxx	uuuu uuuu
TRISD	PORTD Data Direction Register								1111 1111	1111 1111
PSPCON(1)	IBF	OBF	IBOV	PSPMODE	—	—	—	—	0000 ----	0000 ----
MEMCON(2)	EBDIS	—	WAIT1	WAIT0	—	—	WM1	WM0	0-00 --00	0-00 --00

Legend: x = unknown, u = unchanged, — = unimplemented, read as '0'. Shaded cells are not used by PORTD.

Note 1: Enabled only in Microcontroller mode for PIC18F8525/8621 devices.

2: This register is unused on PIC18F6525/6621 devices and reads as '0'.

FIGURE 17-1: SIMPLIFIED BLOCK DIAGRAM OF THE ENHANCED PWM MODULE



Note 1: The 8-bit TMR2 register is concatenated with the 2-bit internal Q clock, or 2 bits of the prescaler, to create the 10-bit time base.

17.4.2 PWM DUTY CYCLE

The PWM duty cycle is specified by writing to the CCPR1L register and to the CCP1CON<5:4> bits. Up to 10-bit resolution is available. The CCPR1L contains the eight MSbs and the CCP1CON<5:4> contains the two LSbs. This 10-bit value is represented by CCPRxL:CCPxCON<5:4>. The PWM duty cycle is calculated by the equation:

EQUATION 17-2:

$$\text{PWM Duty Cycle} = (\text{CCPR1L:CCP1CON<5:4>}) \bullet T_{OSC} \bullet (\text{TMR2 Prescale Value})$$

CCPR1L and CCP1CON<5:4> can be written to at any time but the duty cycle value is not copied into CCPR1H until a match between PR2 and TMR2 occurs (i.e., the period is complete). In PWM mode, CCPR1H is a read-only register.

The CCPRxH register and a 2-bit internal latch are used to double-buffer the PWM duty cycle. This double-buffering is essential for glitchless PWM operation. When the CCPR1H and 2-bit latch match TMR2, concatenated with an internal 2-bit Q clock or two bits of the TMR2 prescaler, the ECCP1 pin is cleared. The maximum PWM resolution (bits) for a given PWM frequency is given by the equation:

EQUATION 17-3:

$$\text{PWM Resolution (max)} = \frac{\log\left(\frac{F_{OSC}}{F_{PWM}}\right)}{\log(2)} \text{ bits}$$

Note:	If the PWM duty cycle value is longer than the PWM period, the ECCP1 pin will not be cleared.

TABLE 17-4: EXAMPLE PWM FREQUENCIES AND RESOLUTIONS AT 40 MHz

PWM Frequency	2.44 kHz	9.77 kHz	39.06 kHz	156.25 kHz	312.50 kHz	416.67 kHz
Timer Prescaler (1, 4, 16)	16	4	1	1	1	1
PR2 Value	FFh	FFh	FFh	3Fh	1Fh	17h
Maximum Resolution (bits)	10	10	10	8	7	6.58

17.4.3 PWM OUTPUT CONFIGURATIONS

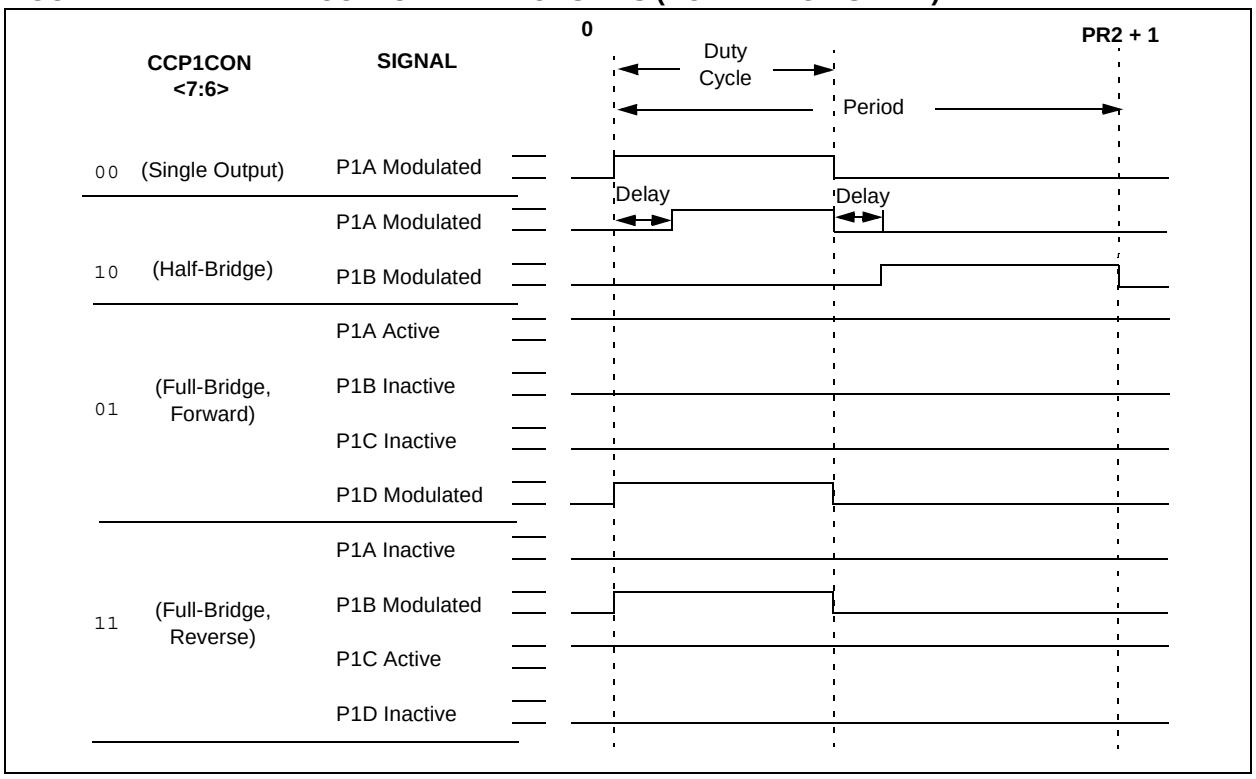
The P1M1:P1M0 bits in the CCP1CON register allow one of four configurations:

- Single Output
- Half-Bridge Output
- Full-Bridge Output, Forward mode
- Full-Bridge Output, Reverse mode

The Single Output mode is the standard PWM mode discussed in **Section 17.4 "Enhanced PWM Mode"**. The Half-Bridge and Full-Bridge Output modes are covered in detail in the sections that follow.

The general relationship of the outputs in all configurations is summarized in Figure 17-2.

FIGURE 17-2: PWM OUTPUT RELATIONSHIPS (ACTIVE-HIGH STATE)



18.0 MASTER SYNCHRONOUS SERIAL PORT (MSSP) MODULE

18.1 Master SSP (MSSP) Module Overview

The Master Synchronous Serial Port (MSSP) module is a serial interface, useful for communicating with other peripheral or microcontroller devices. These peripheral devices may be serial EEPROMs, shift registers, display drivers, A/D converters, etc. The MSSP module can operate in one of two modes:

- Serial Peripheral Interface (SPI)
- Inter-Integrated Circuit (I^2C)
  - Full Master mode
  - Slave mode (with general address call)

The I^2C interface supports the following modes in hardware:

- Master mode
- Multi-Master mode
- Slave mode

18.2 Control Registers

The MSSP module has three associated registers. These include a status register (SSPSTAT) and two control registers (SSPCON1 and SSPCON2). The use of these registers and their individual configuration bits differ significantly depending on whether the MSSP module is operated in SPI or I^2C mode.

Additional details are provided under the individual sections.

18.3 SPI Mode

The SPI mode allows 8 bits of data to be synchronously transmitted and received simultaneously. All four modes of SPI are supported. To accomplish communication, typically three pins are used:

- Serial Data Out (SDO) – RC5/SDO
- Serial Data In (SDI) – RC4/SDI/SDA
- Serial Clock (SCK) – RC3/SCK/SCL

Additionally, a fourth pin may be used when in a Slave mode of operation:

- Slave Select ($\overline{SS}$) – RF7/$\overline{SS}$

Figure 18-1 shows the block diagram of the MSSP module when operating in SPI mode.

FIGURE 18-1: MSSP BLOCK DIAGRAM (SPI™ MODE)

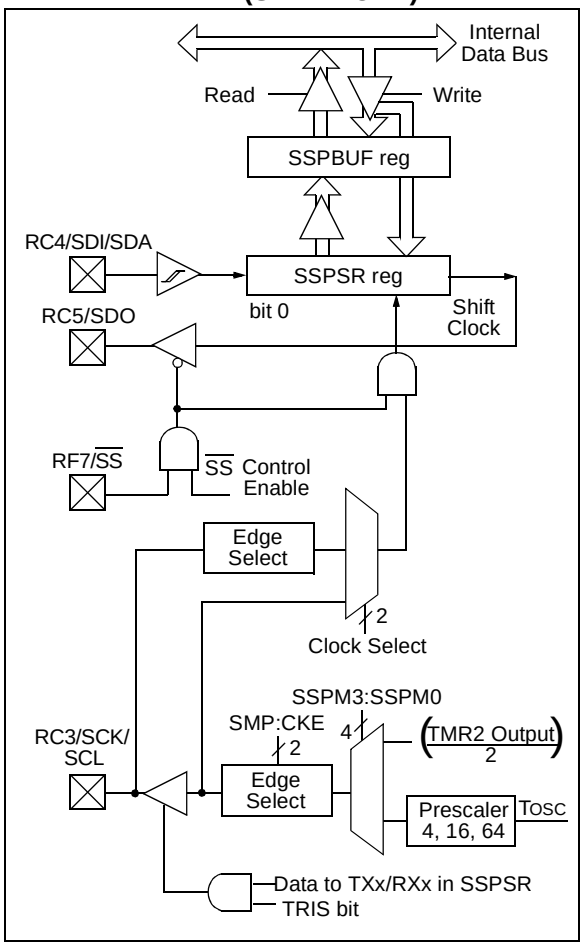
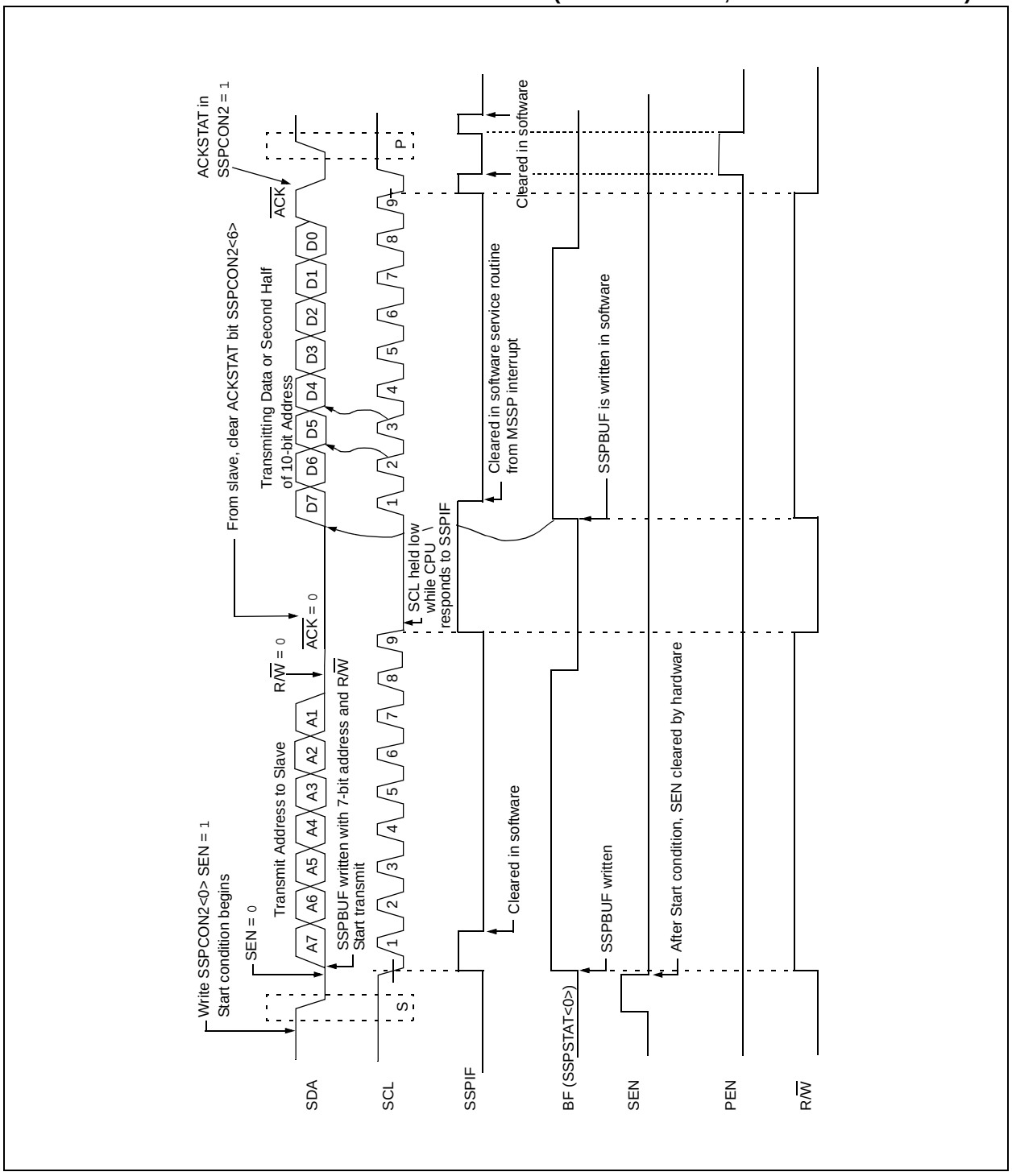


FIGURE 18-21: I²C™ MASTER MODE WAVEFORM (TRANSMISSION, 7 OR 10-BIT ADDRESS)



NOTES:

REGISTER 24-2: CONFIG2L: CONFIGURATION REGISTER 2 LOW (BYTE ADDRESS 300002h)

U-0	U-0	U-0	U-0	R/P-1	R/P-1	R/P-1	R/P-1
—	—	—	—	BORV1	BORV0	BOR	$\overline{\text{PWRTEN}}$
bit 7							bit 0

bit 7-4 **Unimplemented:** Read as '0'

bit 3-2 **BORV1:BORV0:** Brown-out Reset Voltage bits

11 = V_{BOR} set to 2.0V
10 = V_{BOR} set to 2.7V
01 = V_{BOR} set to 4.2V
00 = V_{BOR} set to 4.5V

bit 1 **BOR:** Brown-out Reset Enable bit

1 = Brown-out Reset enabled
0 = Brown-out Reset disabled

bit 0 **$\overline{\text{PWRTEN}}$:** Power-up Timer Enable bit

1 = PWRT disabled
0 = PWRT enabled

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '0'
-n = Value when device is unprogrammed		u = Unchanged from programmed state

REGISTER 24-3: CONFIG2H: CONFIGURATION REGISTER 2 HIGH (BYTE ADDRESS 300003h)

U-0	U-0	U-0	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
—	—	—	WDTPS3	WDTPS2	WDTPS1	WDTPS0	WDTEN
bit 7							bit 0

bit 7-5 **Unimplemented:** Read as '0'

bit 4-1 **WDTPS2:WDTPS0:** Watchdog Timer Postscaler Select bits

1111 = 1:32768
1110 = 1:16384
1101 = 1:8192
1100 = 1:4096
1011 = 1:2048
1010 = 1:1024
1001 = 1:512
1000 = 1:256
0111 = 1:128
0110 = 1:64
0101 = 1:32
0100 = 1:16
0011 = 1:8
0010 = 1:4
0001 = 1:2
0000 = 1:1

bit 0 **WDTEN:** Watchdog Timer Enable bit

1 = WDT enabled
0 = WDT disabled (control is placed on the SWDTEN bit)

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '0'
-n = Value when device is unprogrammed		u = Unchanged from programmed state

TABLE 25-2: PIC18FXXXX INSTRUCTION SET

Mnemonic, Operands		Description	Cycles	16-Bit Instruction Word MSb LSb	Status Affected	Notes
BYTE-ORIENTED FILE REGISTER OPERATIONS						
ADDWF	f, d, a	Add WREG and f	1	0010 01da ffff ffff	C, DC, Z, OV, N	1, 2
ADDWFC	f, d, a	Add WREG and Carry bit to f	1	0010 00da ffff ffff	C, DC, Z, OV, N	1, 2
ANDWF	f, d, a	AND WREG with f	1	0001 01da ffff ffff	Z, N	1,2
CLRF	f, a	Clear f	1	0110 101a ffff ffff	Z	2
COMF	f, d, a	Complement f	1	0001 11da ffff ffff	Z, N	1, 2
CPFSEQ	f, a	Compare f with WREG, skip =	1 (2 or 3)	0110 001a ffff ffff	None	4
CPFSGT	f, a	Compare f with WREG, skip >	1 (2 or 3)	0110 010a ffff ffff	None	4
CPFSLT	f, a	Compare f with WREG, skip <	1 (2 or 3)	0110 000a ffff ffff	None	1, 2
DECF	f, d, a	Decrement f	1	0000 01da ffff ffff	C, DC, Z, OV, N	1, 2, 3, 4
DECFSZ	f, d, a	Decrement f, Skip if 0	1 (2 or 3)	0010 11da ffff ffff	None	1, 2, 3, 4
DCFSNZ	f, d, a	Decrement f, Skip if Not 0	1 (2 or 3)	0100 11da ffff ffff	None	1, 2
INCF	f, d, a	Increment f	1	0010 10da ffff ffff	C, DC, Z, OV, N	1, 2, 3, 4
INCFSZ	f, d, a	Increment f, Skip if 0	1 (2 or 3)	0011 11da ffff ffff	None	4
INFSNZ	f, d, a	Increment f, Skip if Not 0	1 (2 or 3)	0100 10da ffff ffff	None	1, 2
IORWF	f, d, a	Inclusive OR WREG with f	1	0001 00da ffff ffff	Z, N	1, 2
MOVF	f, d, a	Move f	1	0101 00da ffff ffff	Z, N	1
MOVFF	f_s, f_d	Move f_s (source) to 1st word f_d (destination) 2nd word	2	1100 ffff ffff ffff 1111 ffff ffff ffff	None	
MOVWF	f, a	Move WREG to f	1	0110 111a ffff ffff	None	
MULWF	f, a	Multiply WREG with f	1	0000 001a ffff ffff	None	
NEGF	f, a	Negate f	1	0110 110a ffff ffff	C, DC, Z, OV, N	1, 2
RLCF	f, d, a	Rotate Left f through Carry	1	0011 01da ffff ffff	C, Z, N	
RLNCF	f, d, a	Rotate Left f (No Carry)	1	0100 01da ffff ffff	Z, N	1, 2
RRCF	f, d, a	Rotate Right f through Carry	1	0011 00da ffff ffff	C, Z, N	
RRNCF	f, d, a	Rotate Right f (No Carry)	1	0100 00da ffff ffff	Z, N	
SETF	f, a	Set f	1	0110 100a ffff ffff	None	
SUBFWB	f, d, a	Subtract f from WREG with borrow	1	0101 01da ffff ffff	C, DC, Z, OV, N	1, 2
SUBWF	f, d, a	Subtract WREG from f	1	0101 11da ffff ffff	C, DC, Z, OV, N	
SUBWFB	f, d, a	Subtract WREG from f with borrow	1	0101 10da ffff ffff	C, DC, Z, OV, N	1, 2
SWAPF	f, d, a	Swap nibbles in f	1	0011 10da ffff ffff	None	4
TSTFSZ	f, a	Test f, skip if 0	1 (2 or 3)	0110 011a ffff ffff	None	1, 2
XORWF	f, d, a	Exclusive OR WREG with f	1	0001 10da ffff ffff	Z, N	
BIT-ORIENTED FILE REGISTER OPERATIONS						
BCF	f, b, a	Bit Clear f	1	1001 bbba ffff ffff	None	1, 2
BSF	f, b, a	Bit Set f	1	1000 bbba ffff ffff	None	1, 2
BTFSC	f, b, a	Bit Test f, Skip if Clear	1 (2 or 3)	1011 bbba ffff ffff	None	3, 4
BTFSS	f, b, a	Bit Test f, Skip if Set	1 (2 or 3)	1010 bbba ffff ffff	None	3, 4
BTG	f, b, a	Bit Toggle f	1	0111 bbba ffff ffff	None	1, 2

Note 1: When a Port register is modified as a function of itself (e.g., `MOVF PORTB, 1, 0`), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as an input and is driven low by an external device, the data will be written back with a '0'.

2: If this instruction is executed on the TMR0 register (and where applicable, 'd' = 1), the prescaler will be cleared if assigned.

3: If Program Counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a `NOP`.

4: Some instructions are 2-word instructions. The second word of these instructions will be executed as a `NOP` unless the first word of the instruction retrieves the information embedded in these 16 bits. This ensures that all program memory locations have a valid instruction.

5: If the table write starts the write cycle to internal memory, the write will continue until terminated.

MOVLW **Move Literal to W**

Syntax: [*label*] MOVLW k

Operands: $0 \le k \le 255$

Operation: $k \rightarrow W$

Status Affected: None

Encoding:

0000	1110	kkkk	kkkk

Description: The eight-bit literal ‘k’ is loaded into W.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal ‘k’	Process Data	Write to W

Example: `MOVLW 0x5A`

After Instruction
W = 0x5A

MOVWF **Move W to f**

Syntax: [*label*] MOVWF f [,a]

Operands: $0 \le f \le 255$
$a \in [0,1]$

Operation: $(W) \rightarrow f$

Status Affected: None

Encoding:

0110	111a	ffff	ffff

Description: Move data from W to register ‘f’. Location ‘f’ can be anywhere in the 256-byte bank. If ‘a’ is ‘0’, the Access Bank will be selected, overriding the BSR value. If ‘a’ = 1, then the bank will be selected as per the BSR value (default).

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register ‘f’	Process Data	Write register ‘f’

Example: `MOVWF REG, 0`

Before Instruction
W = 0x4F
REG = 0xFF
After Instruction
W = 0x4F
REG = 0x4F

NOTES:

27.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings(†)

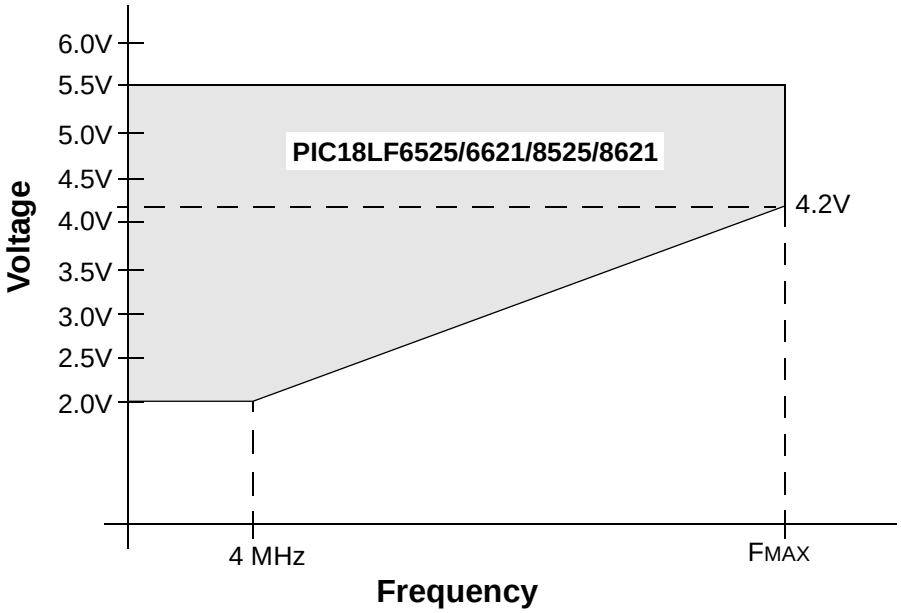
Ambient temperature under bias ..... -40°C to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on any pin with respect to V_{SS} (except V_{DD}, $\overline{MCLR}$ and RA4) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +5.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS} **(Note 2)** ..... 0V to +13.25V
Voltage on RA4 with respect to V_{SS} ..... 0V to +8.5V
Total power dissipation **(Note 1)** 1.0W
Maximum current out of V_{SS} pin ..... 300 mA
Maximum current into V_{DD} pin ..... 250 mA
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ±20 mA
Maximum output current sunk by any I/O pin ..... 25 mA
Maximum output current sourced by any I/O pin ..... 25 mA
Maximum current sunk by all ports ..... 200 mA
Maximum current sourced by all ports ..... 200 mA

Note 1: Power dissipation is calculated as follows:
$P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

2: Voltage spikes below V_{SS} at the $\overline{MCLR}/V_{PP}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{MCLR}/V_{PP}$ pin, rather than pulling this pin directly to V_{SS}.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

FIGURE 27-2: PIC18LF6X2X/8X2X VOLTAGE-FREQUENCY GRAPH (INDUSTRIAL)



For PIC18F6525/6621 and PIC18F8525/8621 in Microcontroller mode:
F_{MAX} = (16.36 MHz/V) ($V_{DDAPPMIN}$ – 2.0V) + 4 MHz, if $V_{DDAPPMIN} \leq 4.2V$;
F_{MAX} = 40 MHz, if $V_{DDAPPMIN} > 4.2V$.

For PIC18F8525/8621 in modes other than Microcontroller mode:
F_{MAX} = (9.55 MHz/V) ($V_{DDAPPMIN}$ – 2.0V) + 4 MHz, if $V_{DDAPPMIN} \leq 4.2V$;
F_{MAX} = 25 MHz, if $V_{DDAPPMIN} > 4.2V$.

Note: $V_{DDAPPMIN}$ is the minimum voltage of the PIC® device in the application.

27.2 DC Characteristics: Power-Down and Supply Current PIC18F6525/6621/8525/8621 (Industrial, Extended) PIC18LF6X2X/8X2X (Industrial) (Continued)

PIC18LF6X2X/8X2X (Industrial)	Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial
PIC18F6525/6621/8525/8621 (Industrial, Extended)	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended

Param No.	Device	Typ	Max	Units	Conditions		
	Module Differential Currents (ΔIWDT, ΔIBOR, ΔILVD, ΔIOSCB, ΔIAD)						
D022 (ΔIWDT)	**Watchdog Timer**	<1	2.0	µA	-40°C	VDD = 2.0V	
		<1	2	µA	+25°C		
		5	20	µA	+85°C		
		3	10	µA	-40°C	VDD = 3.0V	
		3	20	µA	+25°C		
		10	35	µA	+85°C		
		12	25	µA	-40°C	VDD = 5.0V	
		15	35	µA	+25°C		
		20	50	µA	+85°C		
D022A (ΔIBOR)	**Brown-out Reset(4)**	55	115	µA	-40°C to +85°C	VDD = 3.0V	
		105	175	µA	-40°C to +85°C	VDD = 5.0V	
D022B (ΔILVD)	**Low-Voltage Detect(4)**	45	125	µA	-40°C to +85°C	VDD = 2.0V	
		45	150	µA	-40°C to +85°C	VDD = 3.0V	
		45	225	µA	-40°C to +85°C	VDD = 5.0V	
D025 (ΔIOSCB)	**Timer1 Oscillator**	20	27	µA	-10°C	VDD = 2.0V	32 kHz on Timer1
		20	30	µA	+25°C		
		25	35	µA	+70°C		
		22	60	µA	-10°C	VDD = 3.0V	32 kHz on Timer1
		22	65	µA	+25°C		
		25	75	µA	+70°C		
		30	75	µA	-10°C	VDD = 5.0V	32 kHz on Timer1
		30	85	µA	+25°C		
		35	100	µA	+70°C		
D026 (ΔIAD)	**A/D Converter**	<1	2	µA	+25°C	VDD = 2.0V	A/D on, not converting
		<1	2	µA	+25°C	VDD = 3.0V	
		<1	2	µA	+25°C	VDD = 5.0V	

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD;

$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: For RC oscillator configurations, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kΩ.

4: The band gap reference is a shared resource used by both BOR and LVD modules. Enabling both modules will consume less than the specified sum current of the modules.

28.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES

Note:	The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.

"Typical" represents the mean of the distribution at 25°C. "Maximum" or "minimum" represents (mean + 3σ) or (mean – 3σ) respectively, where σ is a standard deviation, over the whole temperature range.

FIGURE 28-1: TYPICAL IDD vs. FOSC OVER VDD (HS MODE)

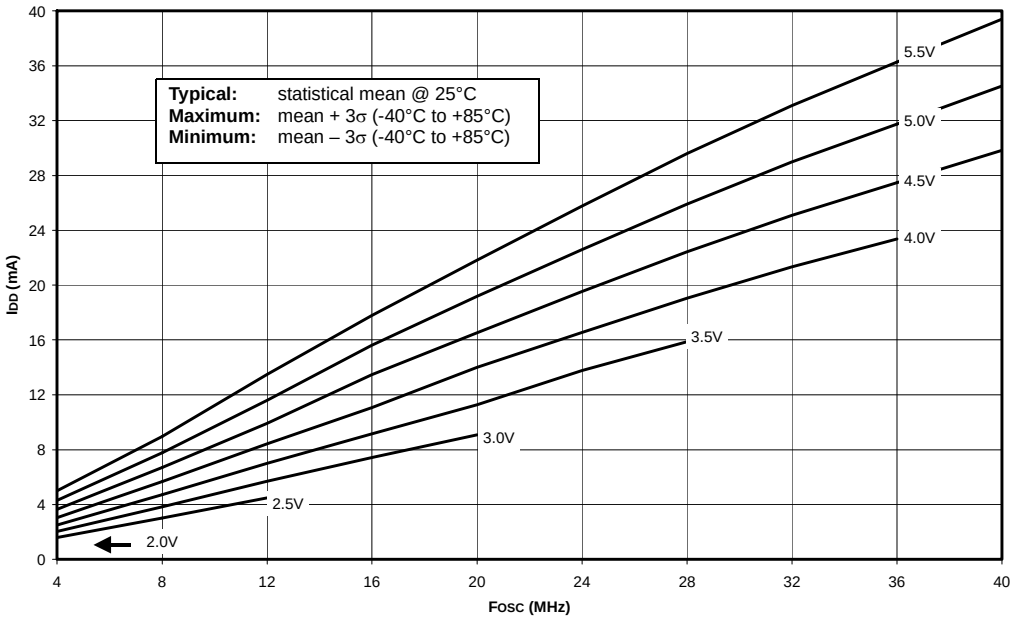


FIGURE 28-2: MAXIMUM IDD vs. FOSC OVER VDD (HS MODE)

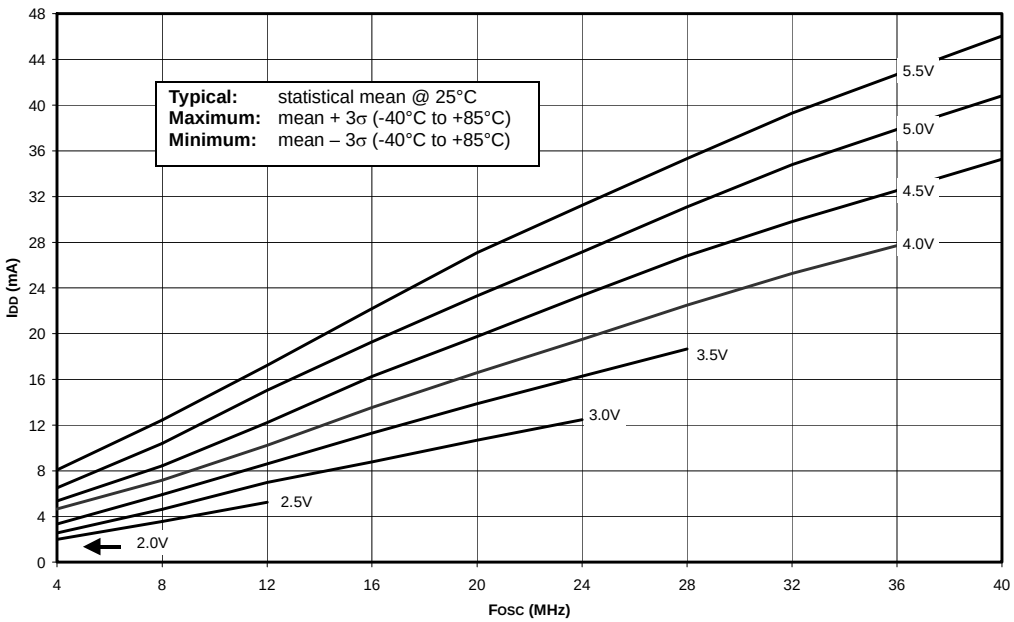


FIGURE 28-13: AVERAGE FOSC vs. VDD FOR VARIOUS Rs (RC MODE, C = 100 pF, TEMP = 25°C)

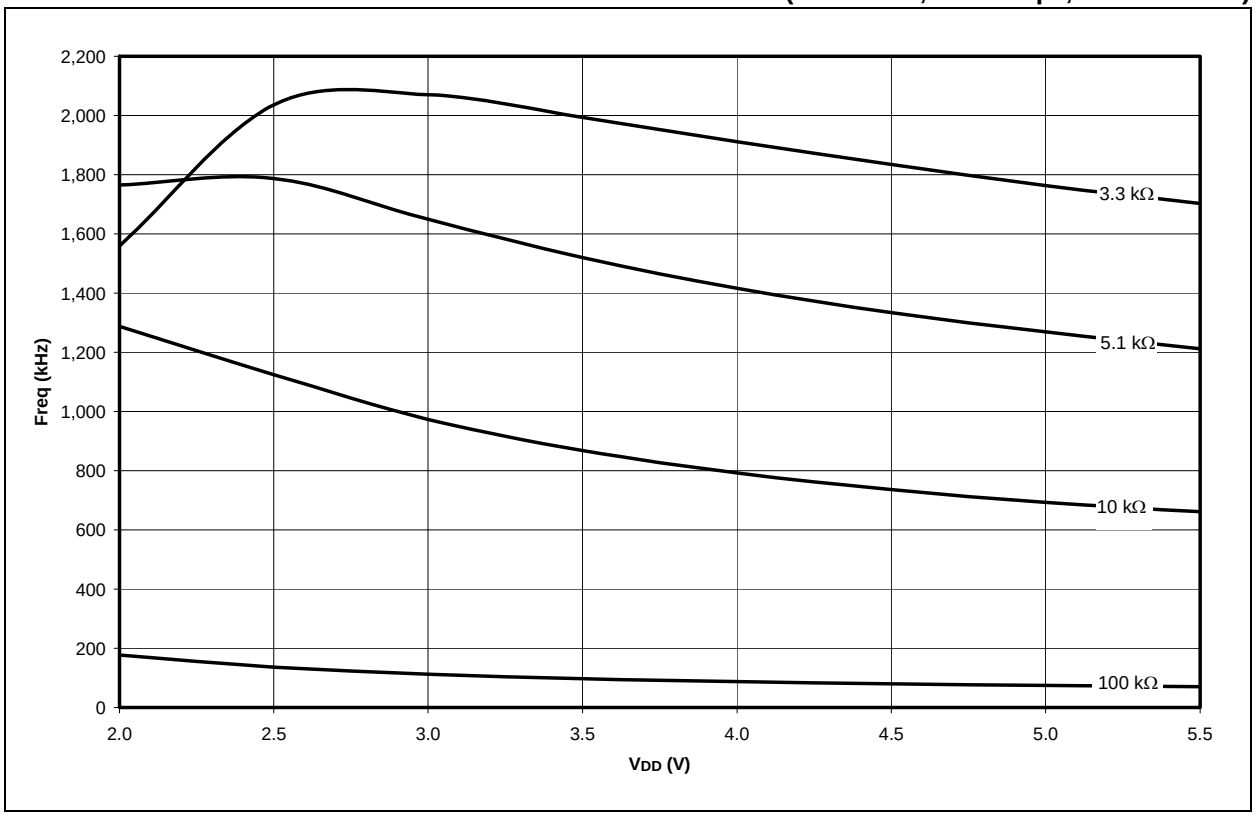


FIGURE 28-14: AVERAGE FOSC vs. VDD FOR VARIOUS Rs (RC MODE, C = 300 pF, TEMP = 25°C)

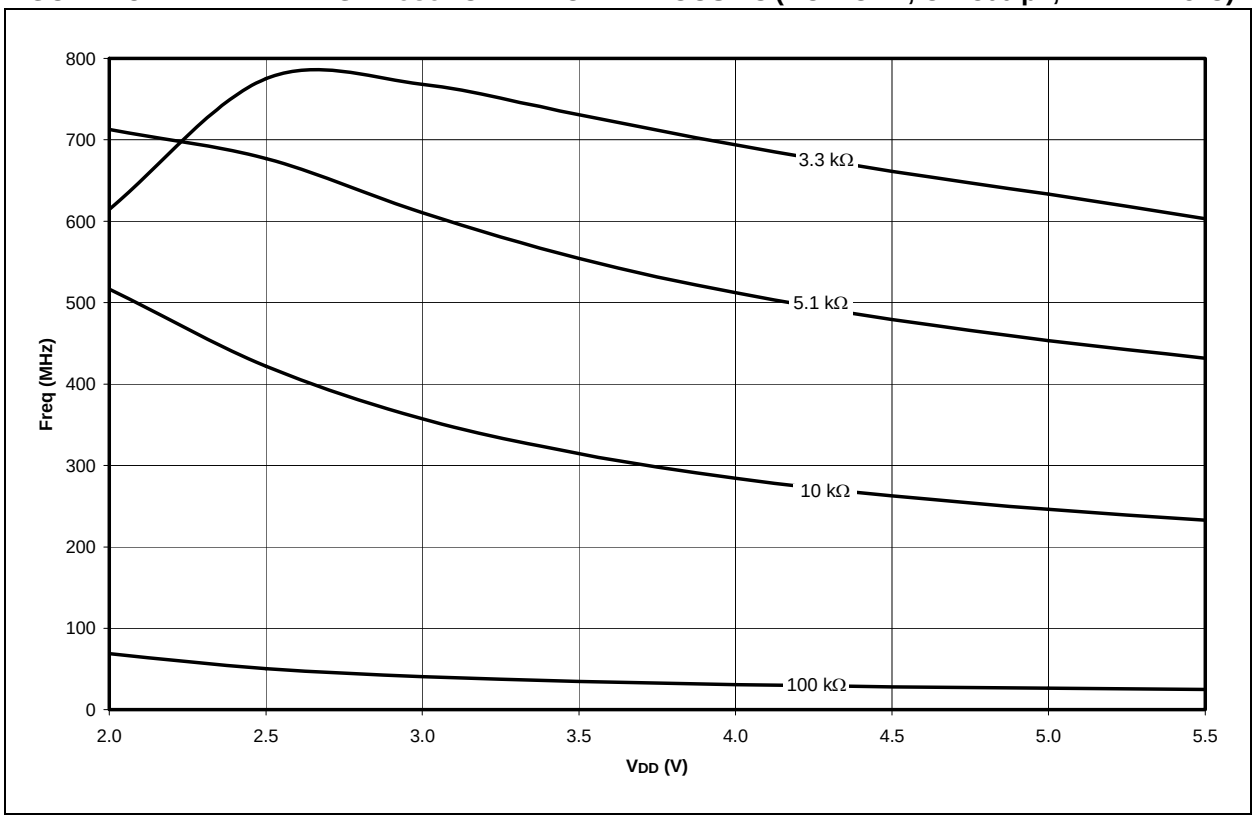


FIGURE 28-21: TYPICAL, MINIMUM AND MAXIMUM V_{OH} vs. I_{OH} (V_{DD} = 5V, -40°C TO +125°C)

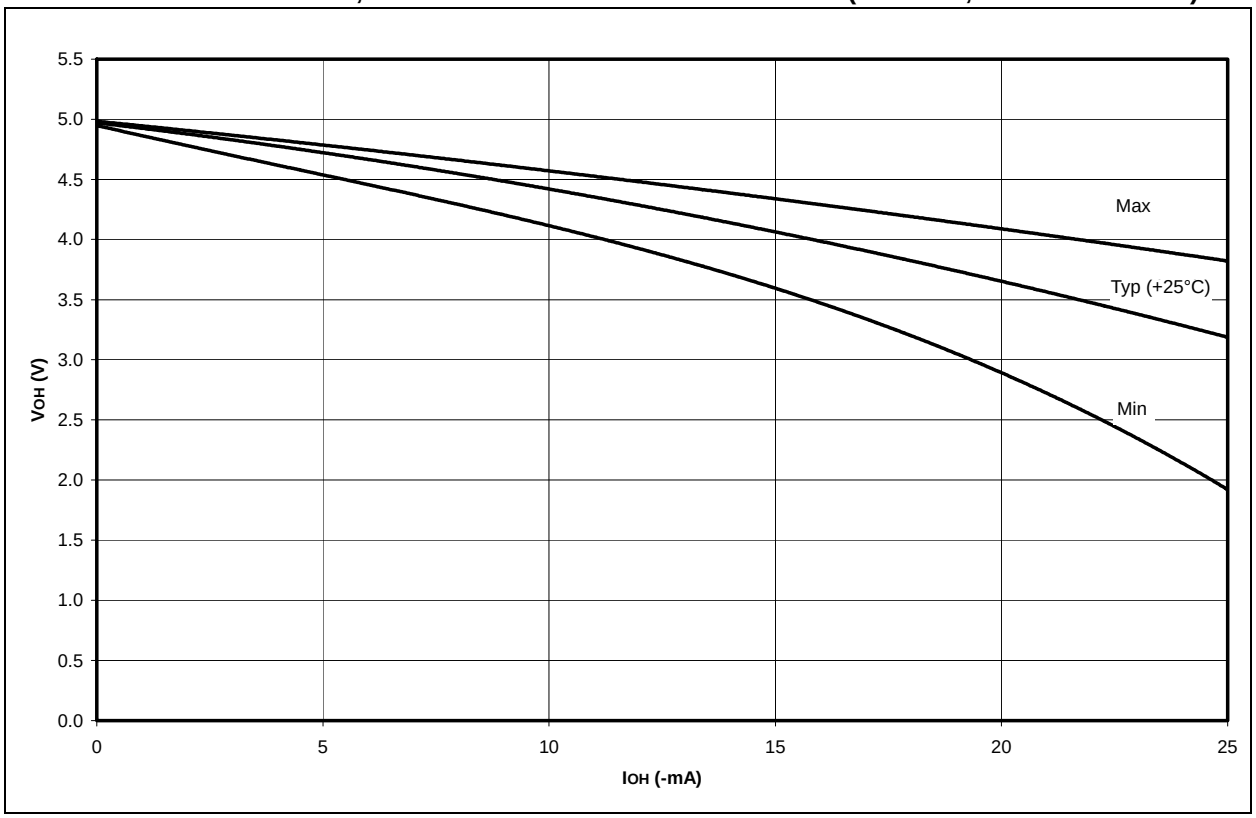
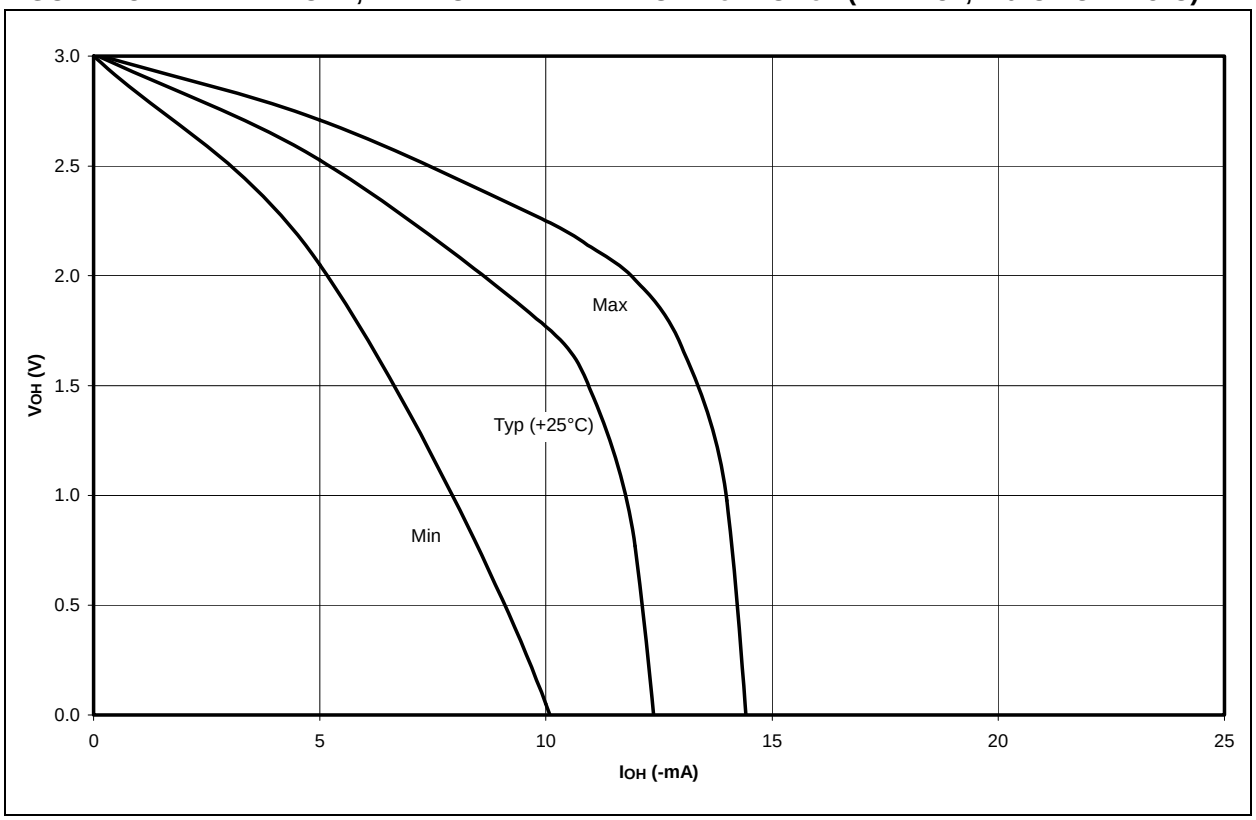


FIGURE 28-22: TYPICAL, MINIMUM AND MAXIMUM V_{OH} vs. I_{OH} (V_{DD} = 3V, -40°C TO +125°C)



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